



B/IFW

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: : Date: 6/2/2004  
Aik Chong Tan et al : Group: 2831  
APPLN. NO. 09/736462 : Examiner: Hung V. Ngo  
FILED: 12/15/2000 :  
FOR: BUMP CHIP LEAD FRAME AND PACKAGE

I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS  
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ON: June 2, 2004

Date of Deposit

SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC  
Name of Assignee

Lydia McNamara  
SIGNATURE

6/3/04  
DATE

SUBMITTAL OF FORMAL DRAWINGS

Honorable Commissioner of Patents and Trademarks,  
Washington, D.C. 20231

Attn: Official Draftsman

SIR:

We are hereby submitting 5 sheets of replacement formal  
drawings for the above-identified patent application.

Respectfully submitted,  
Aik Chong Tan et al by

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